

**HYSOL[®] EE0079/HD0070**
Electronic Formulated Liquid

Formerly Dexter

DescriptionHysol[®] EE0079/HD0070 is an encapsulation system.

Typical Uncured Properties	EE0079	HD0070	Test Method
Color, maximum	Gardner 1	Gardner 2	ASTM D1544
Solids content, %	0	66-72	ASTM D115
Flash Point, °C	68	102	ASTM D3278
Density @ 25°C, gm/cc	1.12-1.14	1.0-1.2	ASTM D1475
Viscosity @ 25°C			ASTM D2393
Brookfield RVF			
Spindle 2, Speed 10, cps	500-700		
Spindle 5, Speed 4, cps		4,500-7,500	
Shelf Life 2 25°C, months			
Minimum from date of shipment	12	12	

Typical Cured Properties	EE0079/HD0070	Test Method
Color	Light Amber	Visual
Coefficient of Linear Thermal Expansion		STP 65B
In/in/°C, (30°C to 90°C)	66×10^{-6}	
Compressive Strength, psi	18,000	STP 92A
Density, gm/cc	1.19	STP 9A
Linear Shrinkage, %	0.60	STP 56D
Hardness, Shore D	85	STP 11A
Tensile Strength, psi	8,000	STP 38A
Elongation, %	5	STP 38A
Thermal Conductivity,		STP 47C
Cal x cm/sec x cm ² x °C	5×10^{-4}	
Flexural Strength, psi	18,000	STP 39A
Heat Deflection Temperature		ASTM D648
@ 264 psi, °C	80	
Izod Impact strength, ft-lb/in. of notch	0.22	ASTM D256
Moisture Absorption, 24 hour		STP 109A
Immersion @ 25°C, %	0.20	
Guide to Operating Class, IEEE °C	105	

Cured Electrical Properties**EE0079/HD0070****Test Method**Dielectric Strength, volts/mil @ 10 mil thick.
Arc Resistance, sec.2,150
92STP 48D
STP 48E**@ 25°C****@ 105°C**

	K		D	K		D
1 KHz	3.8		0.011	5.9		0.782
Vol. Res.		1×10^{16}				5×10^{16}

K = Dielectric Constant by ASTM D150

D = Dissipation Factor by ASTM D 150

Vol. Res. = Volume Resistivity in ohm-cm by ASTM D257

Handling**EE0079/HD0070**

Mix ratio, parts by weight*	100/25
Mix ratio, parts by volume*	100/26
Pot Life @ 25°C, 200 gm mass, minutes	25
Viscosity @ 25°C	
Spindle 5, Speed 20, cps	1,500
Peak exotherm (200 gm mass), °C	200

*Mix ratio of these materials is fixed by their chemistry. Any attempt to increase or decrease the cure rate by adding more or less hardener will result in degraded materials.

If crystallized during storage, heat to 60°C for 2-6 hours (depending on size of container) with occasional stirring.

Cure Schedule

Recommended cure: 2 hours at 60°C. Casting may be cooled to reduce exotherm until gellation. Then post cure 2 hours @ 60°C or 4 hours @ 50°C. Note: guard against Moisture – Use dry environment.

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For additional information in the Americas, please contact one of the following locations:

New York

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FAX: 716.372.6864

Canada

TEL: 905.814.6511

FAX: 905.814.5391

Brazil

TEL: 011.55.11.4143.7000

FAX: 011.55.11.4143.7100

For a complete listing of worldwide locations and information on related products, please visit our website www.loctite.com/electronics

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Users should review the Material Safety Data Sheet (MSDS) and product label for the material to determine possible health hazards, appropriate engineering controls and precautions to be observed in using the material. Copies of the MSDS and label are available upon request
